

# Switch-mode Series PNP Silicon Power Transistors

## MJE5850, MJE5851, MJE5852

The MJE5850, MJE5851 and the MJE5852 transistors are designed for high-voltage, high-speed, power switching in inductive circuits where fall time is critical. They are particularly suited for line operated switch-mode applications.

### Features

- Switching Regulators
- Inverters
- Solenoid and Relay Drivers
- Motor Controls
- Deflection Circuits
- Fast Turn-Off Times
- Operating Temperature Range –65 to +150°C
- 100°C Performance Specified for:
  - ◆ Reversed Biased SOA with Inductive Loads
  - ◆ Switching Times with Inductive Loads
  - ◆ Saturation Voltages
  - ◆ Leakage Currents
- Complementary to the MJE13007 Series
- These Devices are Pb-Free and are RoHS Compliant\*

### MAXIMUM RATINGS

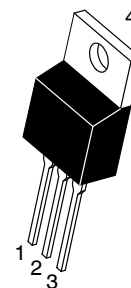
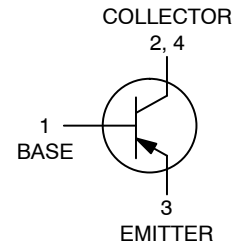
Rating	Symbol	Value	Unit
Collector-Emitter Voltage MJE5850 MJE5851 MJE5852	$V_{CE(sus)}$	300 350 400	Vdc
Collector-Emitter Voltage MJE5850 MJE5851 MJE5852	$V_{CEV}$	350 400 450	Vdc
Emitter Base Voltage	$V_{EB}$	6.0	Vdc
Collector Current – Continuous (Note 1)	$I_C$	8.0	Adc
Collector Current – Peak (Note 1)	$I_{CM}$	16	Adc
Base Current – Continuous (Note 1)	$I_B$	4.0	Adc
Base Current – Peak (Note 1)	$I_{BM}$	8.0	Adc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	$P_D$	80 0.640	W W/°C
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	–65 to 150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Pulse Test: Pulse Width = 5 ms, Duty Cycle ≤ 10%.

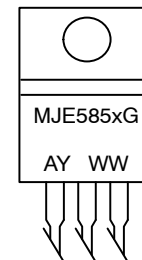
\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**8 AMPERE  
PCP SILICON  
POWER TRANSISTORS  
300–350–400 VOLTS  
80 WATTS**



TO-220  
CASE 221A-09  
STYLE 1

### MARKING DIAGRAM



MJE585x = Device Code  
x = 0, 1, or 2  
G = Pb-Free Package  
A = Assembly Location  
Y = Year  
WW = Work Week

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

NOTE: Some of the device on this data sheet have been **DISCONTINUED**. Please refer to the table on page 7

# MJE5850, MJE5851, MJE5852

## THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.25	$^{\circ}\text{C/W}$
Maximum Lead Temperature for Soldering Purposes: 1/8" from Case for 5 Seconds	$T_L$	275	$^{\circ}\text{C}$

## ELECTRICAL CHARACTERISTICS ( $T_C = 25^{\circ}\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Collector-Emitter Sustaining Voltage ( $I_C = 10\text{ mA}$ , $I_B = 0$ ) MJE5850 MJE5851 MJE5852	$V_{CEO(sus)}$	300 350 400	– – –	– – –	Vdc
Collector Cutoff Current ( $V_{CEV} = \text{Rated Value}$ , $V_{BE(off)} = 1.5\text{ Vdc}$ ) ( $V_{CEV} = \text{Rated Value}$ , $V_{BE(off)} = 1.5\text{ Vdc}$ , $T_C = 100^{\circ}\text{C}$ )	$I_{CEV}$	– –	– –	0.5 2.5	mAdc
Collector Cutoff Current ( $V_{CE} = \text{Rated } V_{CEV}$ , $R_{BE} = 50\ \Omega$ , $T_C = 100^{\circ}\text{C}$ )	$I_{CER}$	–	–	3.0	mAdc
Emitter Cutoff Current ( $V_{EB} = 6.0\text{ Vdc}$ , $I_C = 0$ )	$I_{EBO}$	–	–	1.0	mAdc

### SECOND BREAKDOWN

Second Breakdown Collector Current with base forward biased	$I_{S/b}$	See Figure 12			
Clamped Inductive SOA with base reverse biased	RBSOA	See Figure 13			

### ON CHARACTERISTICS (Note 2)

DC Current Gain ( $I_C = 2.0\text{ Adc}$ , $V_{CE} = 5\text{ Vdc}$ ) ( $I_C = 5.0\text{ Adc}$ , $V_{CE} = 5\text{ Vdc}$ )	$h_{FE}$	15 5	– –	– –	–
Collector-Emitter Saturation Voltage ( $I_C = 4.0\text{ Adc}$ , $I_B = 1.0\text{ Adc}$ ) ( $I_C = 8.0\text{ Adc}$ , $I_B = 3.0\text{ Adc}$ ) ( $I_C = 4.0\text{ Adc}$ , $I_B = 1.0\text{ Adc}$ , $T_C = 100^{\circ}\text{C}$ )	$V_{CE(sat)}$	– – –	– – –	2.0 5.0 2.5	Vdc
Base-Emitter Saturation Voltage ( $I_C = 4.0\text{ Adc}$ , $I_B = 1.0\text{ Adc}$ ) ( $I_C = 4.0\text{ Adc}$ , $I_B = 1.0\text{ Adc}$ , $T_C = 100^{\circ}\text{C}$ )	$V_{BE(sat)}$	– –	– –	1.5 1.5	Vdc

### DYNAMIC CHARACTERISTICS

Output Capacitance ( $V_{CB} = 10\text{ Vdc}$ , $I_E = 0$ , $f_{test} = 1.0\text{ kHz}$ )	$C_{ob}$	–	270	–	pF
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### SWITCHING CHARACTERISTICS

Resistive Load (Table 1)						
Delay Time	(V <sub>CC</sub> = 250 Vdc, I <sub>C</sub> = 4.0 A, I <sub>B1</sub> = 1.0 A, t <sub>p</sub> = 50 μs, Duty Cycle ≤ 2%)	t <sub>d</sub>	–	0.025	0.1	μs
Rise Time		t <sub>r</sub>	–	0.100	0.5	μs
Storage Time	(V <sub>CC</sub> = 250 Vdc, I <sub>C</sub> = 4.0 A, I <sub>B1</sub> = 1.0 A, V <sub>BE(off)</sub> = 5 Vdc, t <sub>p</sub> = 50 μs, Duty Cycle ≤ 2%)	t <sub>s</sub>	–	0.60	2.0	μs
Fall Time		t <sub>f</sub>	–	0.11	0.5	μs
Inductive Load, Clamped (Table 1)						
Storage Time	(I <sub>CM</sub> = 4 A, V <sub>CEM</sub> = 250 V, I <sub>B1</sub> = 1.0 A, V <sub>BE(off)</sub> = 5 Vdc, T <sub>C</sub> = 100°C)	t <sub>sv</sub>	–	0.8	3.0	μs
Crossover Time		t <sub>c</sub>	–	0.4	1.5	μs
Fall Time		t <sub>fi</sub>	–	0.1	–	μs
Storage Time	(I <sub>CM</sub> = 4 A, V <sub>CEM</sub> = 250 V, I <sub>B1</sub> = 1.0 A, V <sub>BE(off)</sub> = 5 Vdc, T <sub>C</sub> = 25°C)	t <sub>sv</sub>	–	0.5	–	μs
Crossover Time		t <sub>c</sub>	–	0.125	–	μs
Fall Time		t <sub>fi</sub>	–	0.1	–	μs

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: PW = 300  $\mu\text{s}$ . Duty Cycle  $\leq 2\%$

TYPICAL ELECTRICAL CHARACTERISTICS

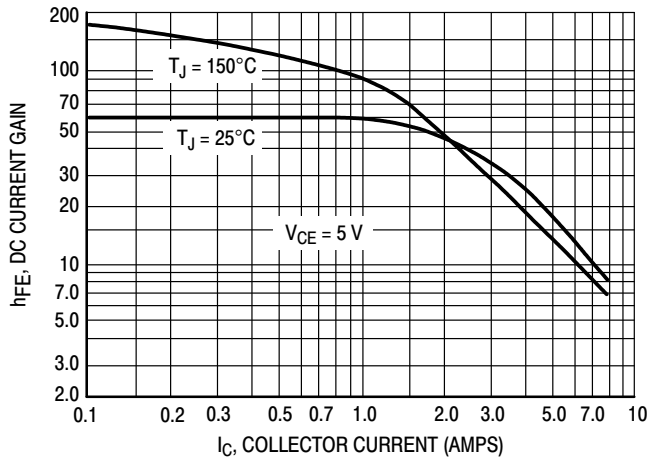


Figure 1. DC Current Gain

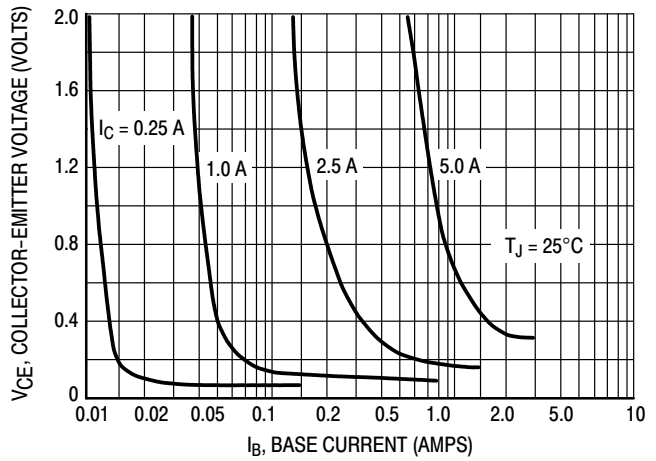


Figure 2. Collector Saturation Region

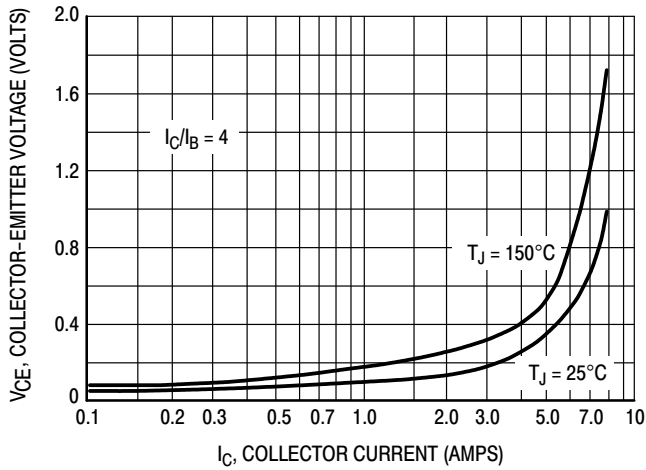


Figure 3. Collector-Emitter Saturation Voltage

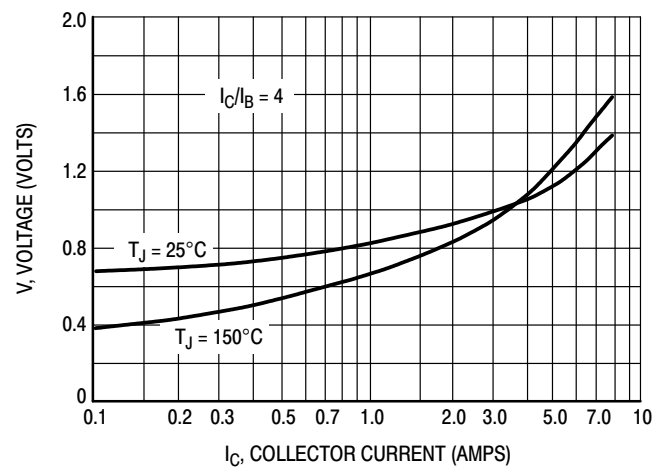


Figure 4. Base-Emitter Voltage

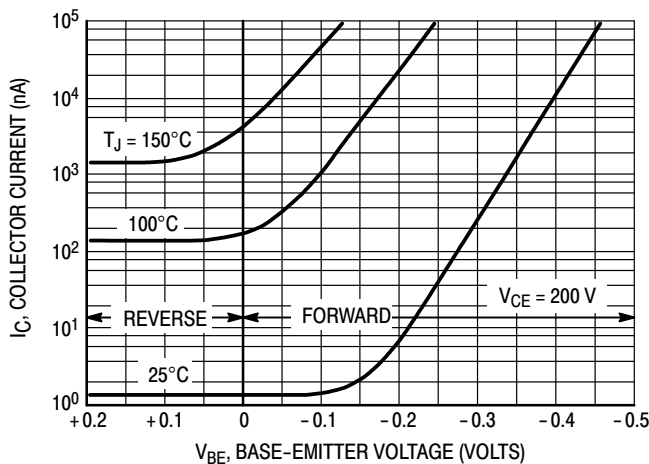


Figure 5. Collector Cutoff Region

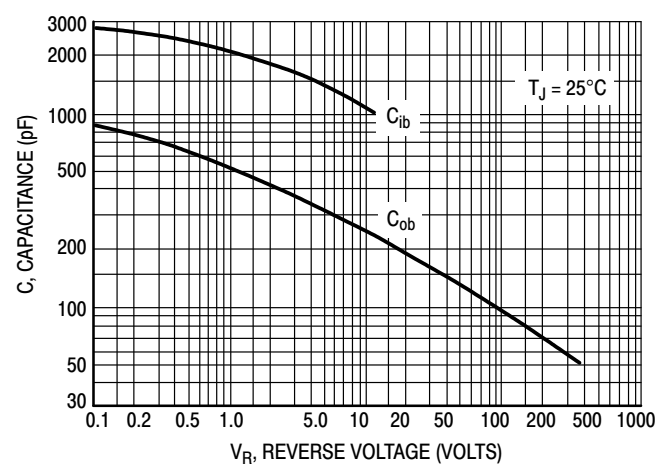
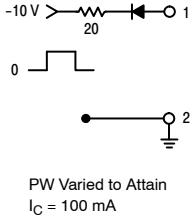
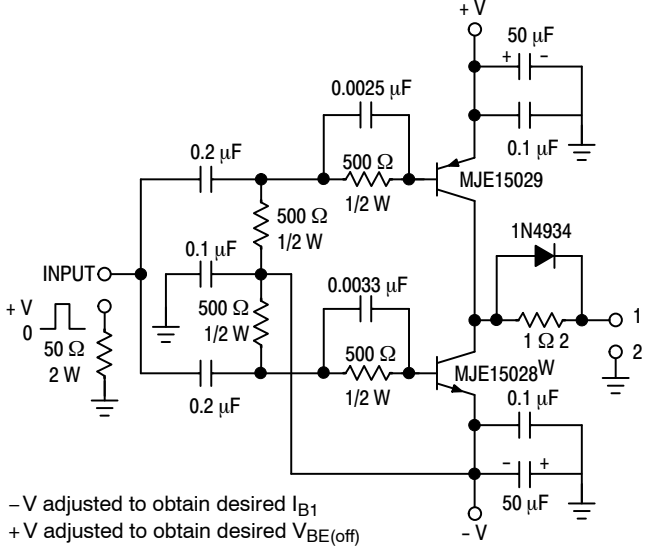
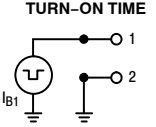
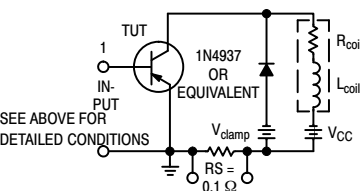
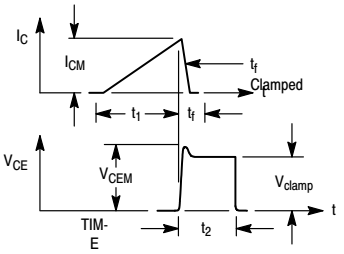
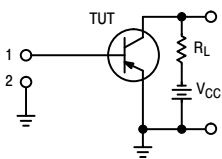


Figure 6. Capacitance

# MJE5850, MJE5851, MJE5852

Table 1. TEST CONDITIONS FOR DYNAMIC PERFORMANCE

	$V_{CEO(sus)}$	RBSOA AND INDUCTIVE SWITCHING	RESISTIVE SWITCHING
INPUT CONDITIONS	 <p>PW Varied to Attain <math>I_C = 100 \text{ mA}</math></p>	 <p><math>-V</math> adjusted to obtain desired <math>I_{B1}</math>  <math>+V</math> adjusted to obtain desired <math>V_{BE(off)}</math></p>	 <p><b>TURN-ON TIME</b>  <math>I_{B1}</math> adjusted to obtain the forced <math>\beta_{FE}</math> desired</p> <p><b>TURN-OFF TIME</b>          Use inductive switching driver as the input to the resistive test circuit.</p>
CIRCUIT VALUES	$L_{coil} = 80 \text{ mH}$ , $V_{CC} = 10 \text{ V}$ $R_{coil} = 0.7 \Omega$	$L_{coil} = 180 \mu\text{H}$ $R_{coil} = 0.05 \Omega$ $V_{CC} = 20 \text{ V}$ $V_{clamp} = 250 \text{ V}$ $R_B$ adjusted to attain desired $I_{B1}$	$V_{CC} = 250 \text{ V}$ $R_L = 62 \Omega$ Pulse Width = $10 \mu\text{s}$
TEST CIRCUITS	<p><b>INDUCTIVE TEST CIRCUIT</b></p>  <p>SEE ABOVE FOR DETAILED CONDITIONS</p>	<p><b>OUTPUT WAVEFORMS</b></p>  <p><math>t_1</math> Adjusted to Obtain <math>I_C</math></p> <p><math>t_1 \approx \frac{L_{coil} (I_{CM})}{V_{CC}}</math></p> <p><math>t_2 \approx \frac{L_{coil} (I_{CM})}{V_{Clamp}}</math></p> <p>Test Equipment          Scope — Tektronix 475 or Equivalent</p>	<p><b>RESISTIVE TEST CIRCUIT</b></p> 

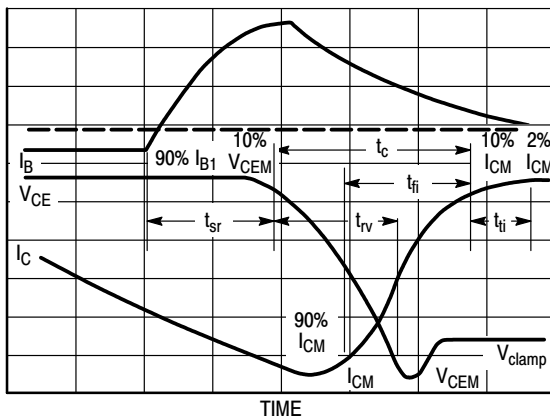


Figure 7. Inductive Switching Measurements

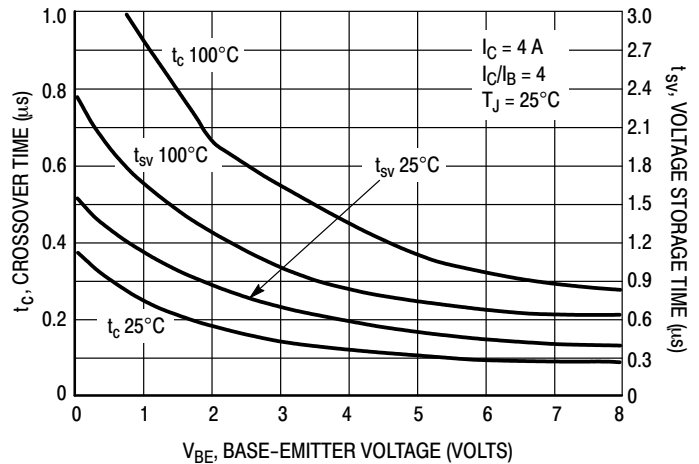


Figure 8. Inductive Switching Times

## SWITCHING TIMES NOTE

In resistive switching circuits, rise, fall, and storage times have been defined and apply to both current and voltage waveforms since they are in phase. However, for inductive loads which are common to SWITCHMODE power supplies and hammer drivers, current and voltage waveforms are not in phase. Therefore, separate measurements must be made on each waveform to determine the total switching time. For this reason, the following new terms have been defined.

$t_{SV}$  = Voltage Storage Time, 90%  $I_{B1}$  to 10%  $V_{CEM}$

$t_{RV}$  = Voltage Rise Time, 10–90%  $V_{CEM}$

$t_{fi}$  = Current Fall Time, 90–10%  $I_{CM}$

$t_{ti}$  = Current Tail, 10–2%  $I_{CM}$

$t_c$  = Crossover Time, 10%  $V_{CEM}$  to 10%  $I_{CM}$

An enlarged portion of the inductive switching waveform is shown in Figure 7 to aid on the visual identity of these terms.

For the designer, there is minimal switching loss during storage time and the predominant switching power losses occur during the crossover interval and can be obtained using the standard equation from AN-222A:

$$P_{SWT} = 1/2 V_{CC} I_C (t_c) f$$

In general,  $t_{RV} + t_{fi} \approx t_c$ . However, at lower test currents this relationship may not be valid.

As is common with most switching transistors, resistive switching is specified at 25°C and has become a benchmark for designers. However, for designers of high frequency converter circuits, the user oriented specifications which make this a “SWITCHMODE” transistor are the inductive switching speeds ( $t_c$  and  $t_{SV}$ ) which are guaranteed at 100°C.

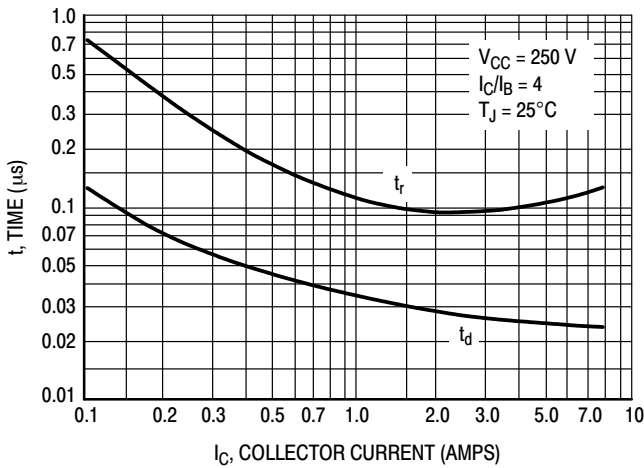


Figure 9. Turn-On Switching Times

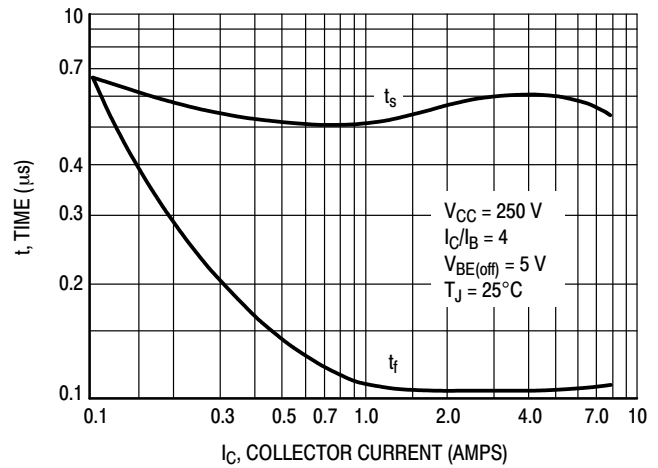


Figure 10. Turn-Off Switching Time

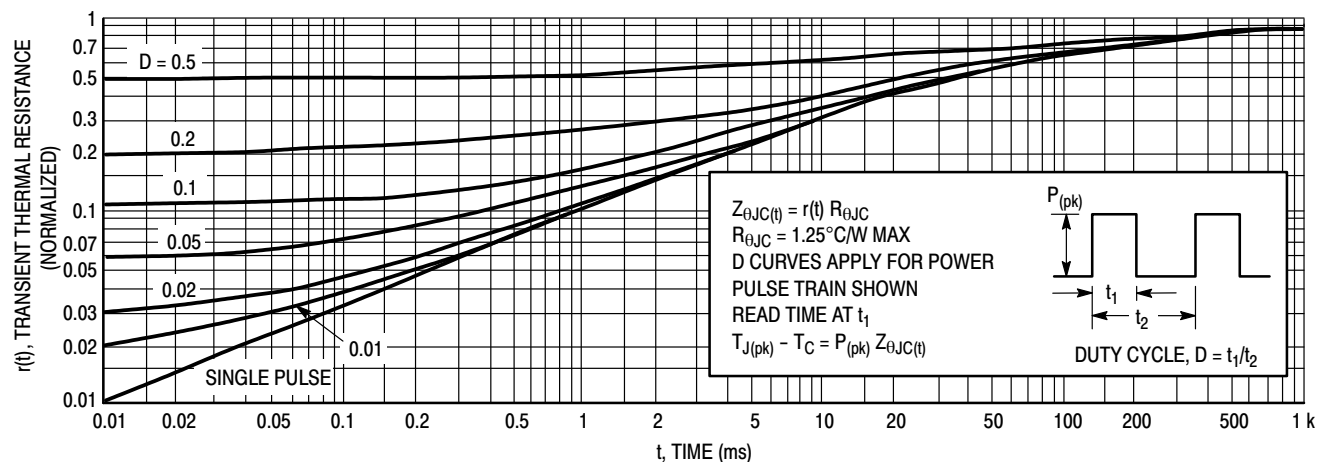


Figure 11. Typical Thermal Response  $[Z_{\theta JC}(t)]$

## MJE5850, MJE5851, MJE5852

The Safe Operating Area figures shown in Figures 12 and 13 are specified for these devices under the test conditions shown.

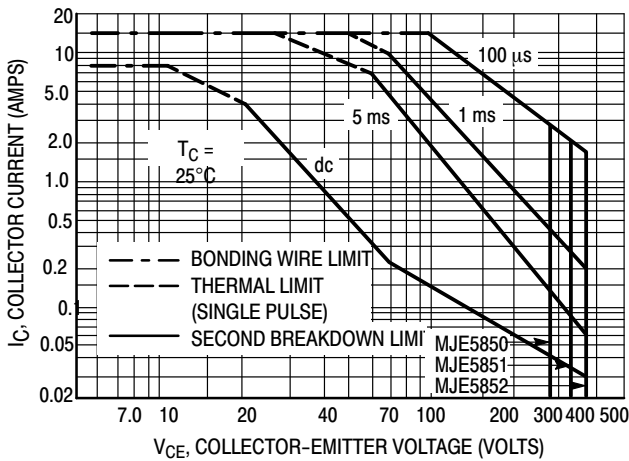


Figure 12. Maximum Forward Bias Safe Operating Area

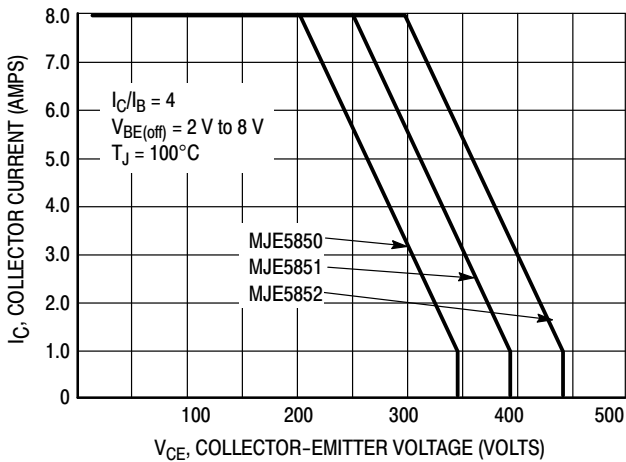


Figure 13. RBSOA, Maximum Reverse Bias Safe Operating Area

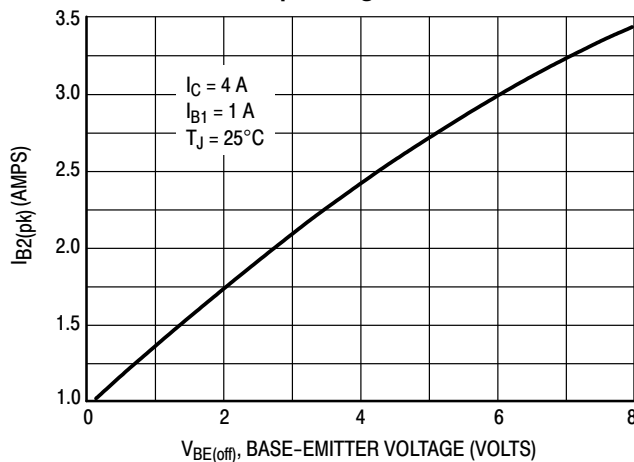


Figure 14. Peak Reverse Base Current

## Safe Operating Area Information

### Forward Bias

There are two limitations on the power handling ability of a transistor average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation, i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 12 is based on  $T_C = 25^\circ\text{C}$ ;  $T_{J(pk)}$  is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when  $T_C \geq 25^\circ\text{C}$ . Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Figure 12 may be found at any case temperature by using the appropriate curve on Figure 15.

$T_{J(pk)}$  may be calculated from the data in Figure 11. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

### Reverse Bias

For inductive loads, high voltage and high current must be sustained simultaneously during turn-off, in most cases, with the base to emitter junction reverse biased. Under these conditions the collector voltage must be held to a safe level at or below a specific value of collector current. This can be accomplished by several means such as active clamping, RC snubbing, load line shaping, etc. The safe level for these devices is specified as Reverse Bias Safe Operating Area and represents the voltage-current condition allowable during reverse biased turn-off. This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode. Figure 13 gives the RBSOA characteristics.

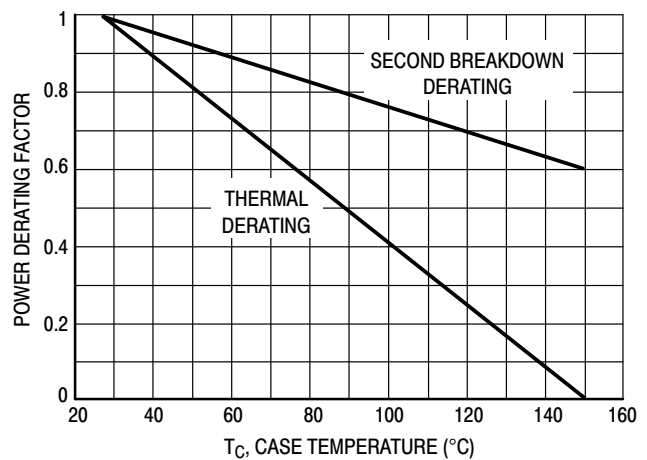


Figure 15. Forward Bias Power Derating

## MJE5850, MJE5851, MJE5852

### ORDERING INFORMATION

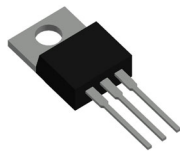
Device	Package	Shipping
MJE5850G	TO-220 (Pb-Free)	50 Units / Rail
MJE5851G	TO-220 (Pb-Free)	50 Units / Rail

### DISCONTINUED (Note 3)

Device	Package	Shipping <sup>†</sup>
MJE5852G	TO-220 (Pb-Free)	50 Units / Rail

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, [BRD8011/D](#).

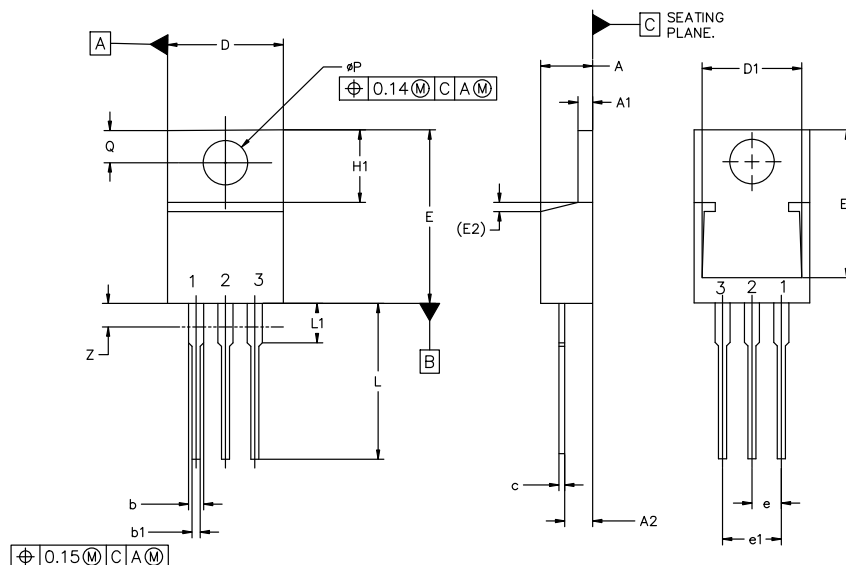
3. **DISCONTINUED:** This device is not recommended for new design. Please contact your **onsemi** representative for information. The most current information on this device may be available on [www.onsemi.com](http://www.onsemi.com).


**TO-220-3 10.10x15.12x4.45, 2.54P**

CASE 221A

ISSUE AL

DATE 05 FEB 2025



MILLIMETERS			
DIM	MIN	NOM	MAX
A	4.07	4.45	4.83
A1	1.15	1.28	1.41
A2	2.04	2.42	2.79
b	1.15	1.34	1.52
b1	0.64	0.80	0.96
c	0.36	0.49	0.61
D	9.66	10.10	10.53
D1	8.43	8.63	8.83
E	14.48	15.12	15.75
E1	12.58	12.78	12.98
E2	1.27 REF		

MILLIMETERS			
DIM	MIN	NOM	MAX
e	2.42	2.54	2.66
e1	4.83	5.08	5.33
H1	5.97	6.22	6.47
L	12.70	13.49	14.27
L1	2.80	3.45	4.10
Q	2.54	2.79	3.04
øP	3.60	3.85	4.09
Z	---	---	3.48

## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

STYLE 1:  
PIN 1. BASE  
2. COLLECTOR  
3. EMITTER  
4. COLLECTOR

STYLE 2:  
PIN 1. BASE  
2. EMITTER  
3. COLLECTOR  
4. EMITTER

STYLE 3:  
PIN 1. CATHODE  
2. ANODE  
3. GATE  
4. ANODE

STYLE 4:  
PIN 1. MAIN TERMINAL 1  
2. MAIN TERMINAL 2  
3. GATE  
4. MAIN TERMINAL 2

STYLE 5:  
PIN 1. GATE  
2. DRAIN  
3. SOURCE  
4. DRAIN

STYLE 6:  
PIN 1. ANODE  
2. CATHODE  
3. ANODE  
4. CATHODE

STYLE 7:  
PIN 1. CATHODE  
2. ANODE  
3. CATHODE  
4. ANODE

STYLE 8:  
PIN 1. CATHODE  
2. ANODE  
3. EXTERNAL TRIP/DELAY  
4. ANODE

STYLE 9:  
PIN 1. GATE  
2. COLLECTOR  
3. EMITTER  
4. COLLECTOR

STYLE 10:  
PIN 1. GATE  
2. SOURCE  
3. DRAIN  
4. SOURCE

STYLE 11:  
PIN 1. DRAIN  
2. SOURCE  
3. GATE  
4. SOURCE

STYLE 12:  
PIN 1. MAIN TERMINAL 1  
2. MAIN TERMINAL 2  
3. GATE  
4. NOT CONNECTED

**DOCUMENT NUMBER:** 98ASB42148B

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**DESCRIPTION:** TO-220-3 10.10x15.12x4.45, 2.54P

**PAGE 1 OF 1**

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